

Application No. 10/017,942

AMENDMENTS TO THE CLAIMS

1. (Cancel)
2. (Cancel)
3. (Cancel)
4. (Cancel)
5. (Cancel)
6. (Cancel)
7. (Cancel)

8. (Previously Presented) A method of packaging electronic devices operating based on acoustic waves, comprising the steps of:
providing a cap wafer having a surface;
trenching recesses into the cap wafer surface at areas near the perimeter of a desired cavity region;
printing material into the recesses and planarizing it such that each filled recess is flush with the cap wafer surface; and
etching away the cap wafer surface, except for the areas of the original recesses, so that the material forms raised ridges to be bonded to a substrate surface in contact with at least one electronic device.

9. (Previously Presented) The method of claim 8, wherein each of the raised ridges is formed slightly inboard from the perimeter of a desired cavity region, each raised ridge composed of a glass frit material for bonding the cap wafer to the substrate surface.

10. (Original) The method of claim 9, wherein a linewidth of the frit is less than 125 μm

Application No. 10/017,942

11. (Previously Presented) The method of claim 8, wherein, after the recesses are formed and the recesses are filled, the raised ridges are fabricated by etching the surrounding cap wafer surface surrounding each filled recess.

12. (Previously Presented) The method of claim 8 wherein the raised ridges form a continuous perimeter around a cavity region such that a hermetic seal is made when the cap wafer is bonded to a wafer or a substrate in contact with an electronic device.

13. (Cancel)